



#14/5-203

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Cabuz et al.

Serial No.: 09/749,171

Examiner: Simkovic, Viktor

Filed: December 27, 2000

Group Art Unit: 2812

For: THIN SILICON MICROMACHINED STRUCTURES

Docket No.: 1100.1116101 (H16-26635)

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**INFORMATION DISCLOSURE STATEMENT AFTER MAILING DATE OF A FINAL ACTION (37 CFR 1.97(d))**

Assistant Commissioner for Patents  
Washington, D.C. 20231

**CERTIFICATE UNDER 37 C.F.R. 1.10:** The undersigned hereby certifies that this paper or papers, as described herein, are being deposited in the United States Postal Service, "Express Mail Post Office to Addressee" having an Express Mail mailing label number of: EV091136155US, in an envelope addressed to: Assistant Commissioner for Patents, Washington, D.C., 20231 on this 22 day of January, 2003.

By

*Lynn Thompson*  
Lynn Thompson

Dear Sir:

Pursuant to the obligations of candor and good faith imposed by 37 C.F.R. 1.56, the documents listed on the attached PTO-1449 are hereby disclosed.

No representation is intended to be made hereby that any of the cited references establishes, by itself or in combination with other information, a prima facie case of unpatentability of any claim of the present case.

The information disclosure statement transmitted herewith is being filed after the mailing date of either a final action under §1.113 or a notice of allowance under §1.311, whichever occurs

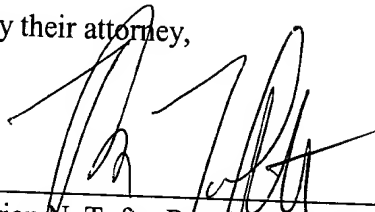
first, but before payment of the issue fee.

Respectfully submitted,

Cabuz et al.

By their attorney,

Dated: January 22, 2003



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